



Material Content Data Sheet



Sales Product Name		BSC010N04LSI		Issued		19. July 2018		
MA#		MA000974064						
Package		PG-TDSON-8-17		Weight*		119.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.27	1.27	12733	12733
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		317	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.70	31.74	316892	317304
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	373	373
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		719	
	plastics	epoxy resin	-	6.079	5.10		51015	
	inorganic material	silicondioxide	60676-86-0	36.646	30.75	35.92	307530	359264
leadfinish	non noble metal	tin	7440-31-5	1.470	1.23	1.23	12334	12334
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1389	1389
solder	noble metal	silver	7440-22-4	0.053	0.04		442	
	non noble metal	tin	7440-31-5	0.042	0.04		353	
	non noble metal	lead	7439-92-1	2.010	1.69	1.77	16872	17667
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	zinc	7440-66-6	0.013	0.01		113	
	non noble metal	iron	7439-89-6	0.269	0.23		2255	
	non noble metal	copper	7440-50-8	10.909	9.15	9.39	91547	93943
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	zinc	7440-66-6	0.026	0.02		222	
	non noble metal	iron	7439-89-6	0.529	0.44		4440	
	non noble metal	copper	7440-50-8	21.482	18.03	18.50	180276	184993
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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